**What is claimed is**

1. A resin particle having an acrylic resin as a main component, having a maximum compression deformation ratio of 60 % or more, and needing a load less than or equal to 60 mN for a compression deformation by 60 %.

2. The resin particle according to claim 1, wherein the load necessary for the compression deformation by 60 % is less than or equal to 30 mN.

3. The resin particle according to claim 1, wherein the resin particle is formed by introducing a treatment liquid containing a monomer with pressure into a medium liquid via a porous membrane to form a droplet of the treatment liquid in the medium liquid and to harden the treatment liquid composing the droplet.

4. The resin particle according to claim 1, wherein the resin particle includes a polymer of monomers containing a urethane compound and an acrylic acid ester.

5. The resin particle according to claim 4, wherein the urethane compound of 5 or more parts by weight is contained with respect to the monomer of 100 parts by weight.

6. The resin particle according to claim 4, wherein the urethane compound of 25 or more parts by weight is contained with respect to the monomer of 100 parts by weight.

7. The resin particle according to claim 4, wherein the urethane compound includes a polyfuctional urethane acrylate.

8. The resin particle according to claim 4, wherein the urethane compound includes a bifunctional urethane acrylate.

9. The resin particle according to claim 1, wherein the acrylic resin includes a polymer of monomers containing either or both an acrylic acid ester having a linear chain structure and an acrylic acid ester having a branching structure.

10. A method for manufacturing a resin particle comprising the steps of:

introducing a treatment liquid containing a monomer with pressure into a medium liquid via a porous membrane;

forming a droplet of the treatment liquid in the medium liquid; and

hardening the treatment liquid composing the droplet to form the resin particle.

11. The method for manufacturing the resin particle according to claim 10,

wherein an acrylic monomer composition added with polymerization initiator is used as the treatment liquid, while water added with a dispersion stabilizer is used as the medium liquid.

12. The method for manufacturing the resin particle according to claim 10, wherein a SPG membrane is used as the porous membrane.

13. A conductive particle comprising:

a rein particle as a core, having an acrylic resin as a main component, having a maximum compression deformation ratio of 60 % or more, and needing a load of less than or equal to 60 mN for a compression deformation by 60 %; and

a conductive material bonded to a surface of the resin particle.

14. The conductive particle according to claim 13, wherein the conductive material is defined as a metallic material.

15. An anisotropic conductive adhesive comprising:

a conductive particle dispersed within a adhesive material;

a resin particle as a core of the conductive particle, the resin particle having an acrylic resin as a main component, having a maximum compression deformation ratio of 60 % or more, and needing a load of less than or equal to 60 mN for a compression deformation by 60 %; and

a conductive material bonded to a surface of the resin particle.

16. The anisotropic conductive adhesive according to claim 15, wherein the adhesive material includes an epoxy material defined as a thermosetting resin and a hardener for hardening the epoxy material.

17. The anisotropic conductive adhesive according to claim 15, wherein the anisotropic conductive adhesive is molded in a film form.